

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Chi-Wei Tien</td><td>03/19/2007</td></tr><tr><td>Chang-Yuan Wu</td><td>03/19/2007</td></tr><tr><td>Ching-Ya Tu</td><td>03/19/2007</td></tr></tbody></table>	Name	Execution Date	Chi-Wei Tien	03/19/2007	Chang-Yuan Wu	03/19/2007	Ching-Ya Tu	03/19/2007	
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Chi-Wei Tien	03/19/2007								
Chang-Yuan Wu	03/19/2007								
Ching-Ya Tu	03/19/2007								
RECEIVING PARTY DATA									
Name:	COMPAL ELECTRONICS, INC.								
Street Address:	No. 581, Jui-Kuang Rd., Nei-Hu Dist.								
City:	Taipei City								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11692926</td></tr></tbody></table>	Property Type	Number	Application Number:	11692926					
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Application Number:	11692926								
CORRESPONDENCE DATA									
Fax Number:	(949)660-0809								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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ATTORNEY DOCKET NUMBER:	20815-US-PA								
NAME OF SUBMITTER:	Belinda Lee								
Total Attachments: 2 source=20815assignment#page1.tif source=20815assignment#page2.tif									

CH 11692926 \$40.00

ASSIGNMENT

WHEREAS,

1. Chi-Wei Tien
3. Ching-Ya Tu

2. Chang-Yuan Wu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **THERMAL CONDUCTING MEDIUM PROTECTOR**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, COMPAL ELECTRONICS, INC.

of No. 581, Jui-Kuang Rd., Nei-Hu Dist., Taipei City, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Tien chiwei Date: Mar. 19, 2007

Sole or First Joint Inventor: Tien Chi-Wei

Signature: Wu Chang-Yuan Date: Mar. 19, 2007

Second Joint Inventor(if any): Wu Chang-Yuan

Signature: Tu Ching Ya Date: Mar. 19, 2007

Third Joint Inventor(if any): Tu Ching Ya

Signature: _____ Date: _____

Fourth Joint Inventor(if any):